

Electronic Patent Application Fee Transmittal

Application Number:	10668914			
Filing Date:	23-Sep-2003			
Title of Invention:	PROCESS AND INTEGRATION SCHEME FOR FABRICATING CONDUCTIVE COMPONENTS, THROUGH-VIAS AND SEMICONDUCTOR COMPONENTS INCLUDING CONDUCTIVE THROUGH-WAFER VIAS			
First Named Inventor/Applicant Name:	Nishant Sinha			
Filer:	Brick Glenn Power/Pyper Stivers			
Attorney Docket Number:	2269-5859US (02-0390.00/U			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appt Issue fee	1501	1	1400	1400
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Total in USD (\$)				1700